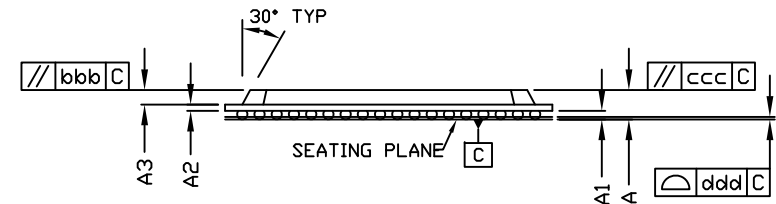


		Symbol	Common Dimensions	
Package :			HSBGA	
Body Size :	X	D	19.00	
	Y	E	19.00	
Ball Pitch :	X	eD	1.00	
	Y	eE	1.00	
Total Thickness :		A	1.71	±0.19
Mold Thickness :		A3	0.85	Ref.
Substrate Thickness :		A2	0.36	Ref.
Ball Diameter :			0.60	
Stand Off :		A1	0.40	~ 0.60
Ball Width :		b	0.50	~ 0.70
Mold Area :	X	M	17.00	
	Y	N	17.00	
Chamfer		CA	1.215	Ref.
Package Edge Tolerance :		aaa	0.20	
Substrate Flatness :		bbb	0.25	
Mold Flatness :		ccc	0.35	
Coplanarity:		ddd	0.15	
Ball Offset (Package) :		eee	0.25	
Ball Offset (Ball) :		fff	0.10	
Ball Count :		n	324	
Edge Ball Center to Center :	X	D1	17.00	
	Y	E1	17.00	
Center Pkg To Adjacent Center Of Ball:	SE	0.50		
	SD	0.50		



DATE: 03/13/15

DESCRIPTION: 324-Ball, HSBGA 19X19mm (with Heat Slug)

PACKAGE CODE: HSB (HSB324)

DOCUMENT CONTROL #: PD-2198

REVISION: --

NOTE :
1. ALL DIMENSIONS ARE IN MILLIMETERS.